

LPA88-11S

Conductor

Description

LPA88-11S is a fritted platinum conductor paste. Continuous operation at high temperatures (up to 1000 °C) is possible.

Key Features

- Chemically resistant



This picture does not show the packaging of LPA88-11S and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≤ 100 milliohms/square (FFT: 8 um)
Viscosity	20 – 40 Pas (25 °C, D = 100/s)
Alloy Ratio	100
Metal	Pt

Recommended Processing Guide

Printing Parameters	Print through a 200 – 325 mesh screen. Level at room temperature for 5 – 10 minutes.
Printing Speed	Up to 10 cm / s
Drying Temperature	Dry at 150 °C for 10 minutes.
Process Temperature (TDS)	Fire in air at a temperature of at least 950 °C (peak) for 10 minutes
Film Thickness	7 – 12 µm
Recommended Thinner	HVS 100
Paste Compatibility	Dielectrics: IP 211 Series Substrates: Al2O3

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Warranty

12 months

Storage

"Store in a dry, cool (2 to 23 °C) and dark place with container tightly shut"

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